

SEMICONDUCTOR INTERNATIONAL

1984 Article Index

This complete index of articles and authors covers the various subjects published in *Semiconductor International* in 1984. The listings are by article under the following categories: Processing, Assembly and Testing; Company Profiles; Business and Market Indicators; and Conference, Exhibitions and Previews. The Author Index at the end of this section indicates the month and page in which an author's work appeared. Reprints are available on a custom basis at reasonable prices in quantities of 500 or more. Contact Art Lehmann, Cahners Publishing Co., Reprint Services, Cahners Plaza 1350 E. Touhy Ave., P.O. Box 5080, Des Plaines, Ill. 60018 (312) 635-8800.

Processing

"Defining the Issues in Wafer Fab," Dan G. Hutcheson, Jan., pg. 46

P.A.R. — "CAD's Interface Between Design and Mask Making," Jan., pg. 128

"E-Beam Lithography: A Story of Dual Identities," Aaron D. Weiss, Feb., pg. 54

"Process Needs Nurture Equipment Design," Pieter S. Burggraaf, Feb., pg. 66

"Processing Linear Devices for Performance and Reliability," Brian E. Hollis, Feb., pg. 76

"Advances Keep Optical Aligners Ahead of Industry," Pieter S. Burggraaf, Feb., pg. 88

"Instruments with Wafer-mapping Capability," Pieter S. Burggraaf, Mar., pg. 52

"Optimizing Wafer Processing via Statistical Design," Rex G. Bryce and Daniel R. Collette, Mar., pg. 71

"Multilayer Resist Processes and Alternatives," Donald Johnson, Mar., pg. 83

"Silica Liners Extend Life of Diffusion Tubes," Don Kempf, Mar., pg. 128

"Computerizing the Process Line: A Must for Automation," Peter H. Singer, Apr., pg. 68

"Purifying Si and SiO₂ Surfaces with Hydrogen Peroxide," Werner Kern, Apr., pg. 94

"Ammonium Persulfate as a Stripping and Cleaning Oxidant," Peter van Zant, Apr., pg. 109

"Ion Beam Technology," Pieter S. Burggraaf, Apr., pg. 128

"Physics of Ion Beam Wafer Processing," Julius J. Muray, Apr., pg. 130

"Focused Ion Beams in Wafer Processing," Gregory Dunn and Edwin M. Kellogg, Apr., pg. 139

"Focused Ion Beam Technology:

Reviewing Applications Research," Mike Hassel Shearer and Gary Cogswell, Apr., pg. 145

"Ionized Cluster Beam Deposition," Allen R. Kirkpatrick, Apr., pg. 148

P.A.R. — "GaAs Process Effluent Control," Apr., pg. 172

"Techniques of Low Pressure Chemical Vapor Deposition," Peter H. Singer, May, pg. 72

"Low Pressure Chemical Vapor Deposition of Tungsten Silicide," D.L. Brors, J.A. Fair, K. Monnig and K.C. Saraswat, May, pg. 82

"Transition to One Micron Technology: Part I," Pieter H. Burggraaf, May, pg. 100

"Transition to One Micron Technology: From VLSI to ULSI," William L. Morgan, May, pg. 101

"Transition to One Micron Technology: Making the Design Transition," Bob Kirk and Tom Daspit, May, pg. 103

"Stepper Pattern Size Errors at One Micron," Hans R. Rottman, May, pg. 112

"Production Issues in Ion Implantation," Pieter S. Burggraaf, May, pg. 128

"Particle Measurements in Medium-Current Ion Implanters," Shawn Hancock and Chuck Yarling, May, pg. 144

"Practical Approach to Monitoring of Implanted Layers," Robert K. Bergland, May, pg. 155

"Rapid Thermal Processing of Titanium Silicide Films," R.A. Powell, C.B. Cooper III and R. Chow, May, pg. 168

"Plasma Etching of Polysilicon: Overview," Aaron D. Weiss, May, pg. 214

"Plasma Etching Using SF₆ and Chlorine Gases," M. Mieth and A. Barker, May, pg. 222

P.A.R. — "Pressure Control in LPCVD System," Marc deFrautier and Jon Goldman, May, pg. 250

P.A.R. — "Direct Thickness Measurement in Lapping Process," May, pg. 258

"The Technology of Clean Room Design," Peter H. Singer, June, pg. 94

"Controlling Airborne Particles," Pieter S. Burggraaf, June, pg. 105

"Process Control for Semiconductor Manufacturing," David M. Campbell and Zahra Ardehali, June, pg. 127

"Transition to One Micron Technology: Part II," Pieter S. Burggraaf, June, pg. 136

"Transition to One Micron Technology: Concepts for World-Class VLSI Manufacturing Plants," William L. Morgan and James R. Burnett, June, pg. 137

"Transition to One Micron Technology: Equipment Productivity Trends in VLSI Manufacturing," Howard Bogert, June, pg. 142

"Transition to One Micron Technology: Part III," Pieter S. Burggraaf, July, pg. 98

"Transition to One Micron Technology: Changing Factors of Process Chemicals," Don L. Tolliver, July, pg. 99

"Transition to One Micron Technology: Resist and Mask Trends," Richard L. Ruddell, July, pg. 104

"Reduction Reticle Trends: Emphasizing 5X," Pieter S. Burggraaf, Aug., pg. 58

"Qualifying Reduction Reticles," Paul Chipman, Aug., pg. 68

"Furnace Loading Systems Review," Ron Iscoff, Aug., pg. 82

"CAD Systems: Mapping Out Tomorrow's ICs," Peter H. Singer, Aug., pg. 96

"Transition to One Micron Technology: Part IV," Pieter S. Burggraaf, Aug., pg. 110

"Codeposition vs Layering of Sputtered Silicide Films," Lee Kammerdiner and Mike Reeder, Aug., pg. 122

"Wafer Scale Integration: An Appraisal," Ron Iscoff, Sept., pg. 62

"Transition to One Micron Technology: Part V," Pieter S. Burggraaf, Sept., pg. 88

"Transition to One Micron Technology: Epilogue," Richard L. Ruddell, Sept., pg. 91

"Si Crystal Growth Trends," Pieter S. Burggraaf, Oct., pg. 54

"GaAs Crystal Growth Trends," Pieter S. Burggraaf, Oct., pg. 60

"Practical Comparison of LEC Production Methods for Si-GaAs," Richard L. Lane, Oct., pg. 68

"Gallium Arsenide: A Practical Alternative to Silicon," Peter H. Singer, Oct., pg. 80

"Photomask Defects: Causes and Solutions," Arthur C. Titus, Oct., pg. 94

"The Silicon Foundry Interface," Terrence A. Johnston, Oct., pg. 108

"Polyimides in Semiconductor Manufacturing," Ron Iscoff, Oct., pg. 116

"Refractory Metals Silicides," David R. McLachlan and Jonathan B. Avins, Oct., pg. 129

P.A.R. — "Cryopump Standardization in Metalization," Walter R. Sobie, Oct., pg. 144

"Robots in the Clean Room," Ron Iscoff, Nov., pg. 50

"Anatomy of a Clean Room Robot," Tom Peterson, Nov., pg. 58

"Sputtering and Interconnect Trends," Pieter Burggraaf, Nov., pg. 70

"Enhanced Magnetron Sputtering of Planarized Silica Coatings," Ping Chang, Nov., pg. 79

"Improved DUV Multilayer Resist Process," C.H. Ting and K.L. Liauw, Nov., pg. 102

1984 Article Index

"Technologies of Photovoltaic Cell Fabrication," Peter H. Singer, Dec., pg. 80

"Evaluation of Commercial E-Beam Resists," Yoichi Takahashi, Dec., pg. 91

Assembly

"Assembly-Packaging Technology Trends," Dan Rose, Jan., pg. 59

"The Fundamentals of Eutectic Die Attach," Leopoldo Valero, May, pg. 236

"Offshore Assembly Plants Striving to Increase Capacity," Ron Iscoff, June, pg. 148

"Teledyne's Hybrid Microelectronics Formula," Pieter S. Burggraaf, July, pg. 54

"Hybrid Packaging in the 1980s at EDI," Pieter S. Burggraaf, July, pg. 58

"Hybrid Wire Bonding Advances," Peter H. Singer, July, pg. 66

"Hybrid Approaches to Chip Interconnection Offer Many Alternatives," Harvey Miller, July, pg. 82

"Improving Bond Yields to Metal Package Leads," Doug Day, July, pg. 90

"Transition to One Micron Technology: Packaging for Performance," James F. Marshall, Aug., pg. 111

"Moisture Content Control Using Alumina Sensor," Carl M. Roberts, Jr., Aug., pg. 134

"Thermal Effect of Die Bond Voids," Dennis R. Olsen and Howard M. Berg, Sept., pg. 71

"Molding Compounds: Meeting the Needs," Pieter S. Burggraaf, Dec., pg. 60

"Advances in Molding Equipment," Ron Iscoff, Dec., pg. 68

Testing

"VLSI Test Systems: Facing the Challenge of Tomorrow," Peter H. Singer, Jan., pg. 82

"Monitored Burn-in of MOS 64K Dynamic RAMs," Jim Eachus, Jon Klema and Scott Walker, Feb., pg. 104

"A Tutorial: Mass Spectrometers and Chromatographs," Aaron D. Weiss, Mar., pg. 112

"Production Test and Repair of 256K DRAMs with Redundancy," Donald M. Stewart, May, pg. 192

"Analyzing High Via Resistance," J.J. Gajda, T.H. Irish and F.G. Trudeau, May, pg. 200

"The Roles and Use of Failure Analysis Service," Pieter S. Burggraaf, Sept., pg. 44

"Testing Ultra High Speed Devices," Peter H. Singer, Sept., pg. 50

"Transition to One Micron: Testing Challenges," G. Dan Hutcheson and Denise Barton, Sept., pg. 89

"Leak Detection in IC Packages," Peter H. Singer, Nov., pg. 91

Company Profiles

"Motorola's Goal: Full Assembly Automation," Pieter S. Burggraaf, Mar., pg. 120

"IC Production for Automobiles," Peter H. Singer, Apr., pg. 118

Business and Market Indicators

Economic Indicators, Cheryl Patstone, Jan., "Strong Economic Growth Expected through 1985," pg. 37; Feb., "Healthy Business Expansion Continues," pg. 39; Mar., "Economic Expansion to Linger," pg. 43; Apr., "Economic Growth Expected to Reach 5.2% in 1984," pg. 49; May, "Economic Outlook Remains Bright," pg. 55; June, "Semiconductor International Industry Forecast," pg. 81; July, "Economic Growth Remains Strong, but Pace Slows," pg. 41; Sept., "Economic Growth Will Continue Well into 1985," pg. 33; Oct., "Economy Shows Strong Upward Momentum," pg. 37; Nov., "Economic Growth Continues to Slow," pg. 41; Dec., "Expansion Will Continue Through next Summer," pg. 43

"The Measure of Your Worth," Aaron Weiss, Jan., pg. 99

Plan/Buy Report, "Market Trends for Deposition Systems," Feb., pg. 42

Plan/Buy Questionnaire, "Plans to Purchase Resists," Feb., pg. 46

Plan/Buy Report, "Trends in Etching Equipment," Mar., pg. 46

Plan/Buy Report, "Trends in Dicing and Bonding Equipment," Apr., pg. 56

Plan/Buy Questionnaire, "Plans to Purchase CAD — Computer Aided Design — Systems," Apr., pg. 57

"Guide to Industry Organizations," Sheila Meyer, June, pg. 159

Plan Buy Questionnaire, "Plans to Purchase Clean Room Products," Aug., pg. 50

Plan/Buy Questionnaire, "Plans to Purchase Hybrid Materials," Oct., pg. 42

Plan/Buy Report, "Clean Room Products," Dec., pg. 48

Plan/Buy Questionnaire, "Plans to Purchase Crystal Growing and Wafer Slicing and Polishing Equipment," Dec., pg. 51

"2nd Annual Achievement Awards," Peter H. Singer, Dec., pg. 106

Conferences, Exhibitions and Previews

Semicon/Europa '84, Exhibitors Listing and Product Preview, Jan., pg. 115

Product Literature Update Service, Mar., pg. 95

"Preview: Semicon West '84," Overview of Programs and Events, Apr., pg. 160

Semicon West '84, "The Challenge: Automating the Industry," May, pg. 270

Semicon West '84 Exhibitors Listing, May, pg. 277

Semicon East, "Increased Capacity, Automation, Materials' Purity Highlight Semicon East," Aug., pg. 154

IEEE International Test Conference Coverage, Sept., pg. 118

"Southwest Semiconductor Exposition Focuses on Productivity Yield," Sept., pg. 128

Product Literature Update Service, Oct., pg. 215

Semicon Japan '84, Exhibitors List and Technical Sessions, Oct., pg. 159

Semicon Southwest, Exhibitors List and Technical Sessions, Oct., pg. 178

Materials Research Society, Exhibitors List and Technical Sessions, Oct., pg. 190

Product Literature Update Service, Oct., pg. 215

1984 Product Showcase, Nov., pg. 114

American Vacuum Society, Exhibitors List, Technical Sessions, Short Courses and Product Preview, Nov., pg. 178

Advanced Semiconductor Equipment Exposition, Exhibitors List and Technical Sessions, Dec., pg. 119

Authors

Bergland, Robert K., May, pg. 155

Bogert, Howard, June, pg. 142

Brors, D.L.; Fair, J.A.; Monning, K. and Saraswat, K.C., May, pg. 82

Bryce, Rex G. and Collette, Daniel R., Mar., pg. 71

Burggraaf, Pieter S., Feb., pg. 66; Feb., pg. 88; Mar., pg. 52; Mar., pg. 120;

Apr., pg. 128; May, pg. 100; May, pg. 128; June, pg. 105; June, pg. 136; July, pg. 54; July, pg. 58; July, pg. 98; Aug., pg. 58; Aug., pg. 110; Sept., pg. 44; Sept., pg. 88; Oct., pg. 54; Oct., pg. 60; Nov., pg. 70; Dec., pg. 60

Campbell, David M. and Ardehali, Zahra, June, pg. 127

Chang, Ping, Nov., pg. 79

Day, Doug, July, pg. 90

DeFrautier, Marc and Goldman, Jon, May, pg. 250

Dunn, Gregory and Kellogg, Edwin M., Apr., pg. 139

Eachus, Jim; Klema, Jon and Walker, Scott, pg. 104

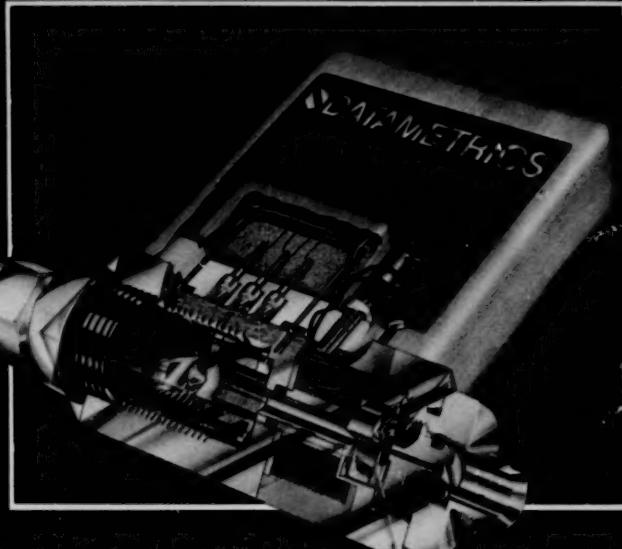
Gajda, J.J.; Irish, T.H. and Trudeau, F.G., May, pg. 200

Hall, David, May, pg. 182

Hancock, Shawn and Yarling, Chuck,

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176/SEMICONDUCTOR INTERNATIONAL, DECEMBER 1984

1984 Article Index

May, pg. 144
Hollis, Brian E., Feb., pg. 76
Hutcheson, Dan G., Jan., pg. 46
Iscoff, Ron, June, pg. 148; Aug., pg. 82; Sept., pg. 62; Oct., pg. 116; Nov., pg. 50; Dec., pg. 68
Johnson, Donald, Mar., pg. 83
Johnston, Terrence, Oct., pg. 108
Kammerdiner, Lee and Reeder, Mike, Aug., pg. 122
Kempf, Don, Mar., pg. 128
Kern, Werner, Apr., pg. 148
Kirk, Bob and Daspit, Tom, May, pg. 103
Kirkpatrick, Allen R., Apr., pg. 148
Lane, Richard L., Oct., pg. 68
Lee, John, Sept., pg. 101
Mahalingam, Mali; Nagarkar, Madhukar; Lofgran, Lynn; Andrews, James; Olsen, Dennis R. and Berg, Howard M., Sept., pg. 71
Marshall, James F., Aug., pg. 111
McLachlan, David R. and Avins, Jonathan B., Oct., pg. 129
Meyer, Sheila, June, pg. 159
Mieth, M. and Barker, A., May, pg. 222
Miller, Harvey, July, pg. 82
Morgan, William L. and Burnett, James R., June, pg. 137
Olsen, Dennis R. and Berg, Howard M., Sept., pg. 71
Patstone, Cheryl, Jan., pg. 37; Feb., pg. 39; Mar., pg. 43; Apr., pg. 49; May, pg. 55; June, pg. 81; July, pg. 45; Aug., pg. 41; Sept., pg. 33; Oct., pg. 37; Nov., pg. 41; Dec., pg. 43
Peterson, Tom, Nov., pg. 58
Powell, R.A.; Cooper, C.B. III and Chow, R., May, pg. 168
Roberts, Carl M., Jr., Aug., pg. 134
Rottman, Hans R., May, pg. 112
Ruddell, Richard L., July, pg. 104; Sept., pg. 91
Shearer, Mike Hassell and Cogswell, Gary, Apr., pg. 145
Singer, Peter H., Jan., pg. 82; Mar., pg. 60; Apr., pg. 68; May, pg. 72; June, pg. 94; July, pg. 66; Aug., pg. 96; Sept., pg. 50; Oct., pg. 80; Nov., pg. 91; Dec., pg. 80; pg. 106
Sobie, Walter R., Oct., pg. 144
Stewart, Donald, M., May, pg. 192
Takahashi, Yoichi, Dec., pg. 91
Ting, C.H. and Liauw, K.L., Nov., pg. 102
Titus, Arthur C., Oct., pg. 94
Tolliver, Don L., July, pg. 99
Turino, Jon, Jan., pg. 70
Valero, Leopoldo, May, pg. 236
VanZant, Peter, Apr., pg. 109
Weiss, Aaron D., Jan., pg. 99; Feb., pg. 54; Mar., pg. 112; May, pg. 214